DATA SHEET

SEMICONDUCTOR EPM

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Electrochemical deposition in manual system

Pure metal and alloy deposition as Au, Ag, Cu, Sn, Ni, SnAg for different applications in semiconductor and microsystem technologies. Enhanced liquid flow and electrical field control ensure a homogenous deposition at highest plating rates. The plating tool operates manually and can be installed in R&D environments as well as in small production lines.

Areas of application

- Current redistribution layers for opto- and microelectronics
- Solder, Cu and Au bumps for wafer level packaging (WLP)
- Functional metallic layers for Micro - Electro - Mechanical Systems (MEMS)
- Micro forming and moulding for microsystems

Features and benefits

- Modular design
- Very small footprint
- Single side processing with isolated contacts
- Edge exclusion < 3mm
- Convertible for 2“, 3“, 4“, 5“, 6“, 8“
- Corresponding etching and drying modules available
- Compatible with automatic tools
- Low budget solution with high performance
- Various options available: pH-control, automatic dosage, forward/reverse puls plating, fire retardent mainbody, etc.
- Customised solutions with various plating chemicals
- Self-explanatory recipe and process control – easy to create, change and check on the monitor
- Operator friendly
- High quality
- > 15 years experience in plating tools

Fountain plater
rotating substrate

Fountain plater
single side
including bevel

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Modular Design

Technical Data EPM

Process	• Manual loading • Electrochemical deposition • Rinsing • Manual unloading	
Dimensions	475 x 1550 x 2050 mm per module (length x width x height)	
Throughput	Depending on process	
Wafer thickness	› 400 µm	
Media	• Electricity • Exhaust • Compressed dry air for pneumatics	380-400V / 50-60Hz / 32A max. 500 m³/h per module

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